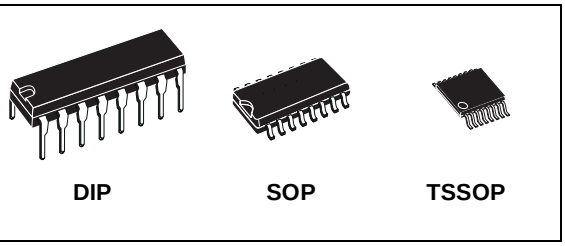
M74HC368

HEX BUS BUFFER WITH 3 STATE OUTPUT INVERTING

- HIGH SPEED:
  t_{PD} = 9ns (TYP.) at V_{CC} = 6V
- LOW POWER DISSIPATION:
  I_{CC} = 4µA(MAX.) at T_A=25°C
- HIGH NOISE IMMUNITY:
  $V_{NIH} = V_{NIL}$ = 28 % V_{CC} (MIN.)
- SYMMETRICAL OUTPUT IMPEDANCE:
  $|I_{OH}| = I_{OL}$ = 6mA (MIN)
- BALANCED PROPAGATION DELAYS:
  $t_{PLH} \cong t_{PHL}$
- WIDE OPERATING VOLTAGE RANGE:
  V_{CC} (OPR) = 2V to 6V
- PIN AND FUNCTION COMPATIBLE WITH 74 SERIES 368



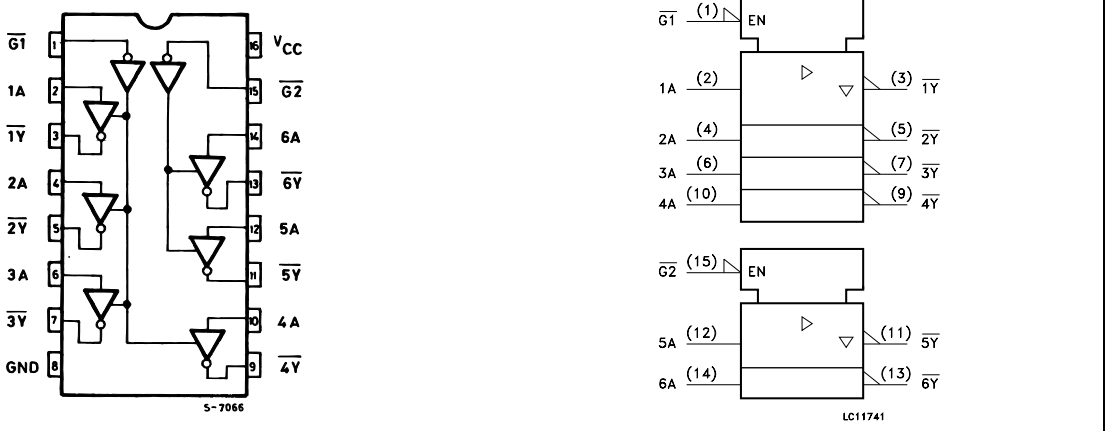
ORDER CODES

PACKAGE	TUBE	T & R
DIP	M74HC368B1R	
SOP	M74HC368M1R	M74HC368RM13TR
TSSOP		M74HC368TTR

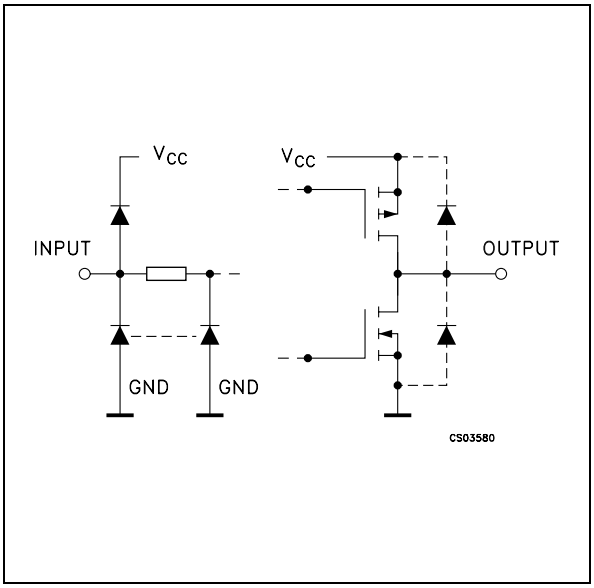
DESCRIPTION

The M74HC368 is an high speed CMOS HEX BUS BUFFER 3-STATE OUTPUTS fabricated with silicon gate C^2MOS technology.
This device contains six buffers, four buffers are controlled by an enable input ($\overline{G1}$) and the other two buffers are controlled by the other enable input ($\overline{G2}$); the outputs of each buffer group are enabled when $\overline{G1}$ and/or $\overline{G2}$ inputs are held low, and when held high, these outputs are disabled in a high-impedance state.
All inputs are equipped with protection circuits against static discharge and transient excess voltage.

PIN CONNECTION AND IEC LOGIC SYMBOLS



INPUT AND OUTPUT EQUIVALENT CIRCUIT



PIN DESCRIPTION

PIN No	SYMBOL	NAME AND FUNCTION
1, 15	$\overline{G1}$, $\overline{G2}$	3 State Output Enable Input
2, 4, 6, 10, 12, 14	1A to 6A	Data Inputs
3, 5, 7, 9, 11, 13	$\overline{1Y}$ to $\overline{6Y}$	Data Outputs
8	GND	Ground (0V)
16	V_{CC}	Positive Supply Voltage

TRUTH TABLE

INPUTS		OUTPUTS
$\overline{G}$	An	$\overline{Yn}$
L	L	H
L	H	L
H	X	Z

X: Don't Care
Z: High Impedance

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	Supply Voltage	-0.5 to +7	V
V_I	DC Input Voltage	-0.5 to V_{CC} + 0.5	V
V_O	DC Output Voltage	-0.5 to V_{CC} + 0.5	V
I_{IK}	DC Input Diode Current	± 20	mA
I_{OK}	DC Output Diode Current	± 20	mA
I_O	DC Output Current	± 35	mA
I_{CC} or I_{GND}	DC V_{CC} or Ground Current	± 70	mA
P_D	Power Dissipation	500(*)	mW
T_{stg}	Storage Temperature	-65 to +150	°C
T_L	Lead Temperature (10 sec)	300	°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied
(*) 500mW at 65 °C; derate to 300mW by 10mW/°C from 65°C to 85°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Value	Unit
V_{CC}	Supply Voltage		2 to 6	V
V_I	Input Voltage		0 to V_{CC}	V
V_O	Output Voltage		0 to V_{CC}	V
T_{op}	Operating Temperature		-55 to 125	°C
t_r, t_f	Input Rise and Fall Time	V_{CC} = 2.0V	0 to 1000	ns
		V_{CC} = 4.5V	0 to 500	ns
		V_{CC} = 6.0V	0 to 400	ns

DC SPECIFICATIONS

Symbol	Parameter	Test Condition		Value							Unit
		V_{CC} (V)		T_A = 25°C			-40 to 85°C		-55 to 125°C		
				Min.	Typ.	Max.	Min.	Max.	Min.	Max.	
V_{IH}	High Level Input Voltage	2.0		1.5			1.5		1.5		V
		4.5		3.15			3.15		3.15		
		6.0		4.2			4.2		4.2		
V_{IL}	Low Level Input Voltage	2.0				0.5		0.5		0.5	V
		4.5				1.35		1.35		1.35	
		6.0				1.8		1.8		1.8	
V_{OH}	High Level Output Voltage	2.0	I_O=-20 µA	1.9	2.0		1.9		1.9		V
		4.5	I_O=-20 µA	4.4	4.5		4.4		4.4		
		6.0	I_O=-20 µA	5.9	6.0		5.9		5.9		
		4.5	I_O=-6.0 mA	4.18	4.31		4.13		4.10		
		6.0	I_O=-7.8 mA	5.68	5.8		5.63		5.60		
V_{OL}	Low Level Output Voltage	2.0	I_O=20 µA		0.0	0.1		0.1		0.1	V
		4.5	I_O=20 µA		0.0	0.1		0.1		0.1	
		6.0	I_O=20 µA		0.0	0.1		0.1		0.1	
		4.5	I_O=6.0 mA		0.17	0.26		0.33		0.40	
		6.0	I_O=7.8 mA		0.18	0.26		0.33		0.40	
I_I	Input Leakage Current	6.0	V_I = V_{CC} or GND			± 0.1		± 1		± 1	µA
I_{OZ}	High Impedance Output Leakage Current	6.0	V_I = V_{IH} or V_{IL} V_O = V_{CC} or GND			± 0.5		± 5		± 10	µA
I_{CC}	Quiescent Supply Current	6.0	V_I = V_{CC} or GND			4		40		80	µA

AC ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Input $t_r = t_f$ = 6ns)

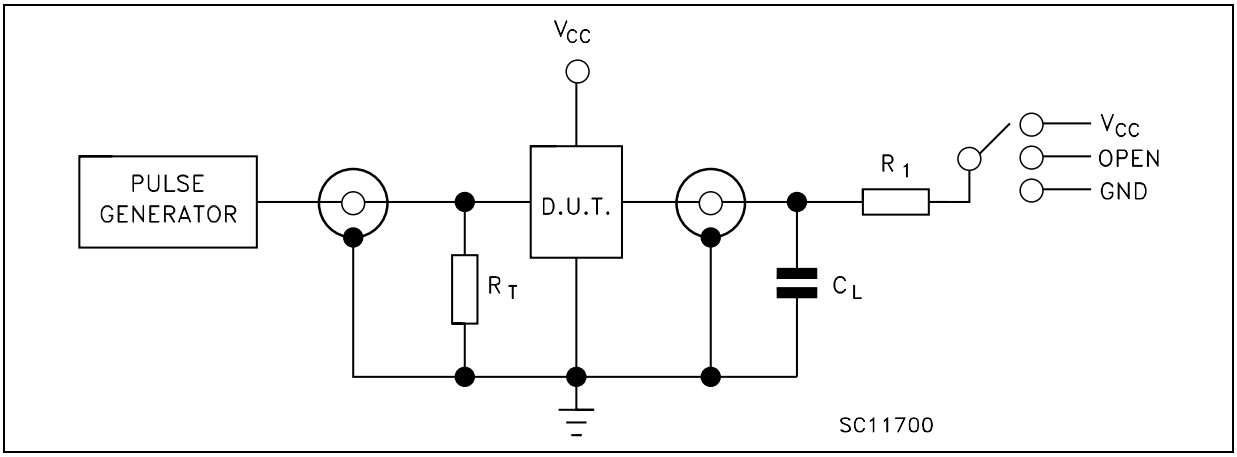
Symbol	Parameter	Test Condition			Value							Unit
		V_{CC} (V)	C_L (pF)		T_A = 25°C			-40 to 85°C		-55 to 125°C		
					Min.	Typ.	Max.	Min.	Max.	Min.	Max.	
t_{TLH} t_{THL}	Output Transition Time	2.0	50			25	60		75		90	ns
		4.5				7	12		15		18	
		6.0				6	10		13		15	
t_{PLH} t_{PHL}	Propagation Delay Time	2.0	50			30	85		105		130	ns
		4.5				10	17		21		26	
		6.0				9	14		18		22	
		2.0	150			42	105		130		160	ns
		4.5				14	21		26		32	
		6.0				12	18		22		27	
t_{PZL} t_{PZH}	High Impedance Output Enable Time	2.0	50	R_L = 1 KΩ		36	90		115		135	ns
		4.5				11	18		23		27	
		6.0				9	15		20		23	
		2.0	150	R_L = 1 KΩ		49	110		140		165	ns
		4.5				15	22		28		33	
		6.0				13	19		24		28	
t_{PLZ} t_{PHZ}	High Impedance Output Disable Time	2.0	50	R_L = 1 KΩ		32	95		120		145	ns
		4.5				14	19		24		29	
		6.0				12	16		20		25	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Test Condition			Value							Unit
		V_{CC} (V)			T_A = 25°C			-40 to 85°C		-55 to 125°C		
					Min.	Typ.	Max.	Min.	Max.	Min.	Max.	
C_{IN}	Input Capacitance					5	10		10		10	pF
C_{PD}	Power Dissipation Capacitance (note 1)					33						pF

1) C_{PD} is defined as the value of the IC's internal equivalent capacitance which is calculated from the operating current consumption without load. (Refer to Test Circuit). Average operating current can be obtained by the following equation. $I_{CC(opr)} = C_{PD} \times V_{CC} \times f_{IN} + I_{CC}/6$ (per Channel)

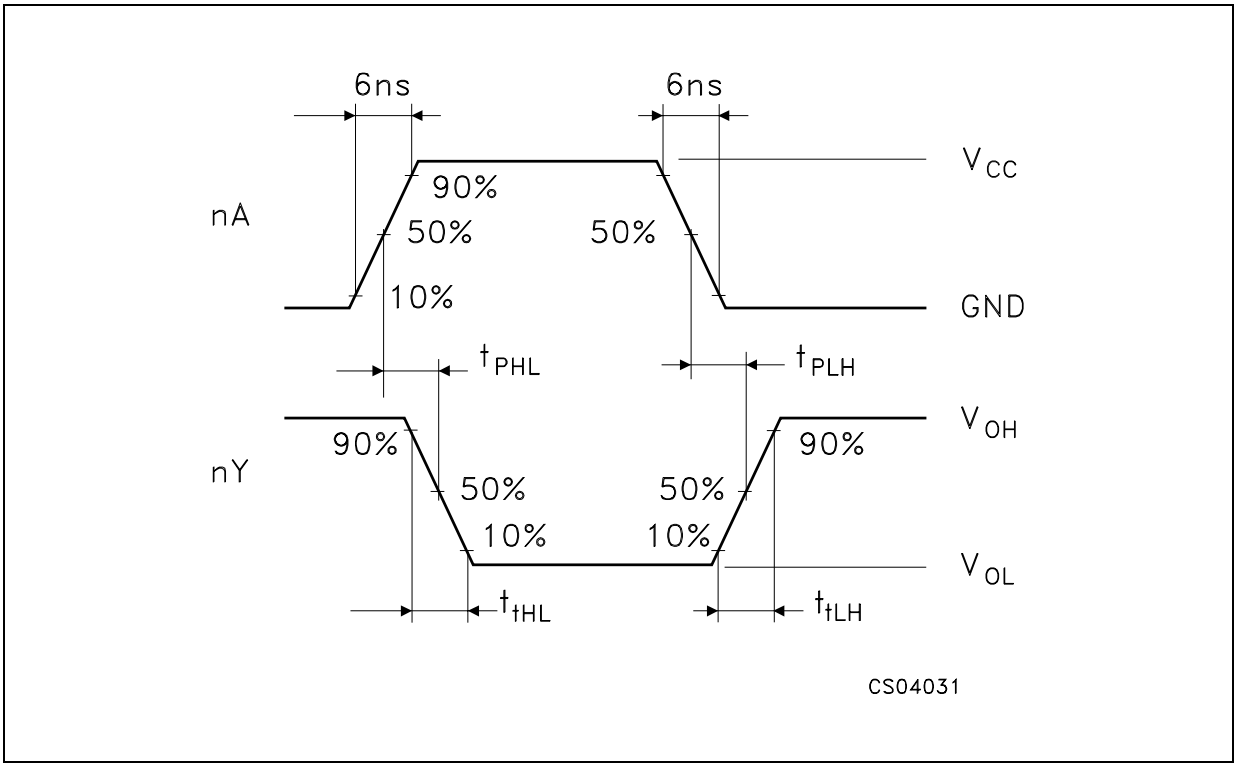
TEST CIRCUIT



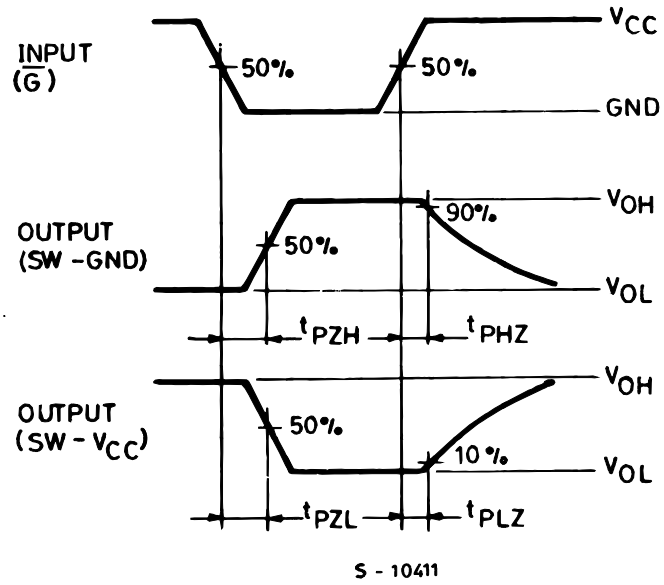
TEST	SWITCH
t_{PLH}, t_{PHL}	Open
t_{PZL}, t_{PLZ}	V_{CC}
t_{PZH}, t_{PHZ}	GND

C_L = 50pF/150pF or equivalent (includes jig and probe capacitance)
R_1 = 1KΩ or equivalent
R_T = Z_{OUT} of pulse generator (typically 50Ω)

WAVEFORM 1:PROPAGATION DELAY TIMES (f=1MHz; 50% duty cycle)

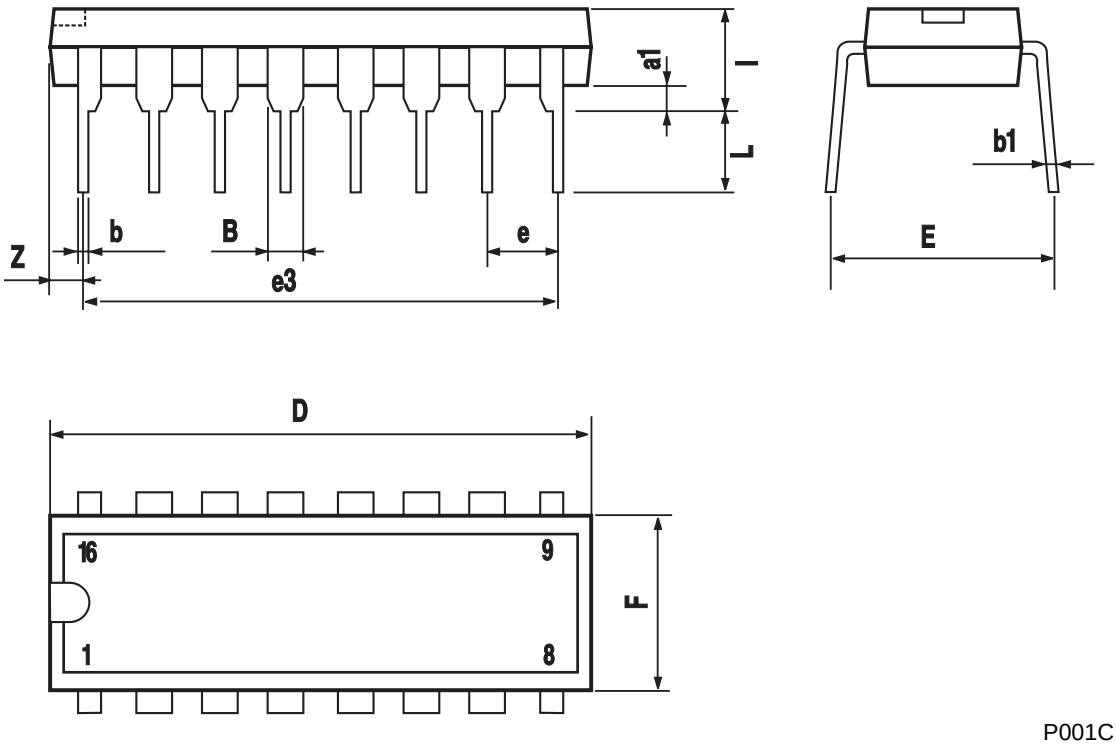


WAVEFORM 2 : OUTPUT ENABLE AND DISABLE TIMES (f=1MHz; 50% duty cycle)



Plastic DIP-16 (0.25) MECHANICAL DATA

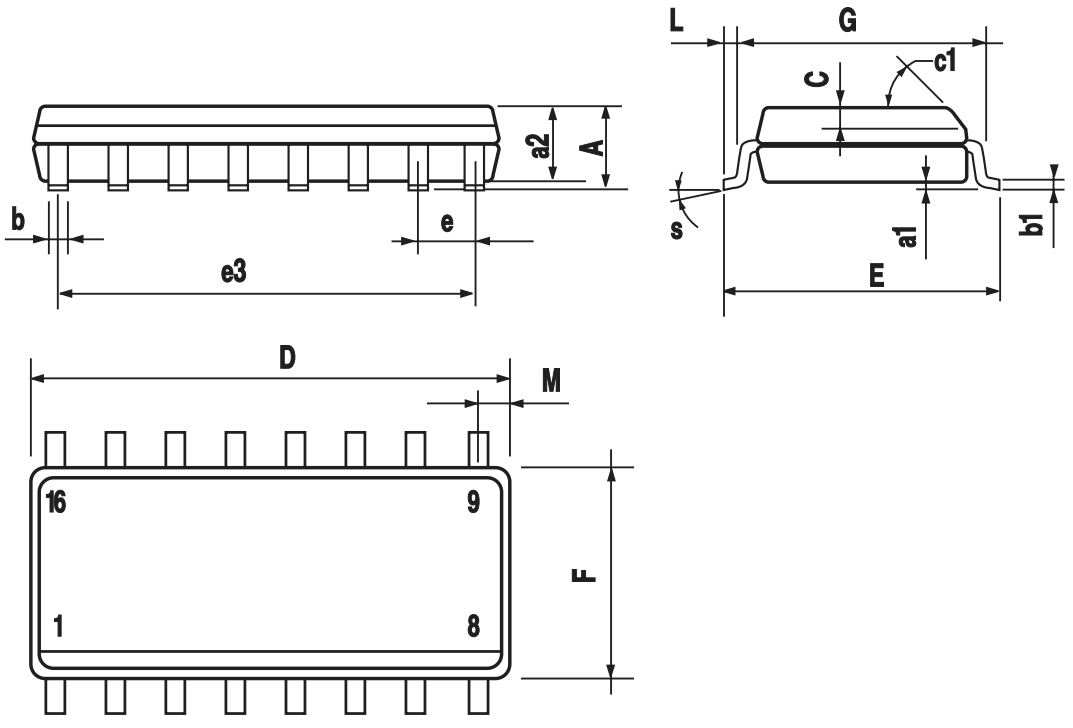
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
B	0.77		1.65	0.030		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		17.78			0.700	
F			7.1			0.280
I			5.1			0.201
L		3.3			0.130	
Z			1.27			0.050



P001C

SO-16 MECHANICAL DATA

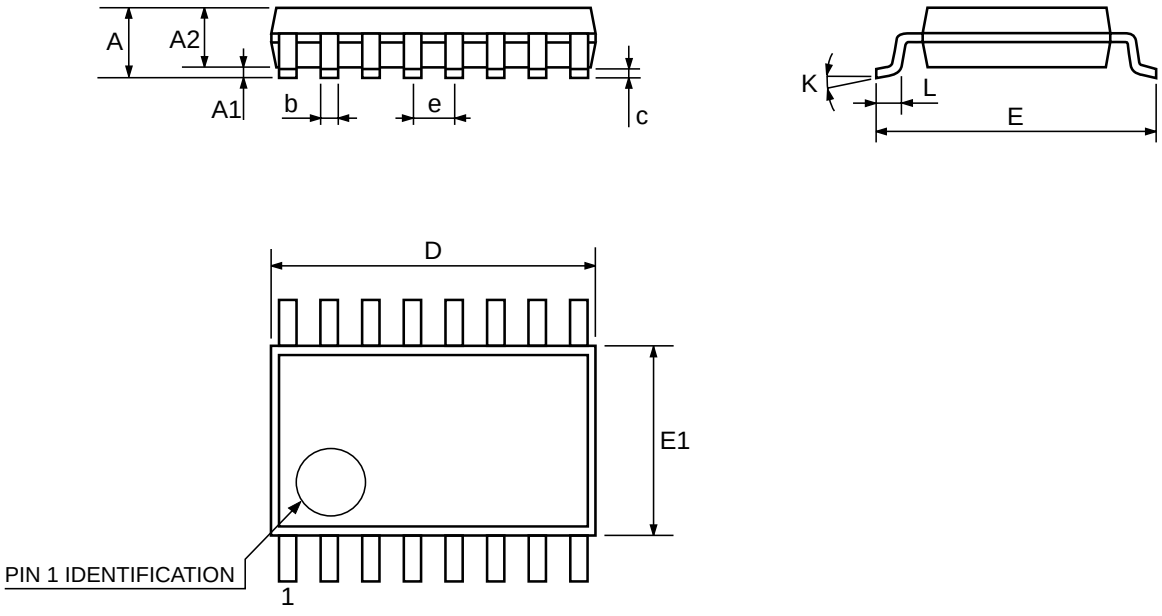
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			1.75			0.068
a1	0.1		0.2	0.003		0.007
a2			1.65			0.064
b	0.35		0.46	0.013		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.019	
c1	45° (typ.)					
D	9.8		10	0.385		0.393
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		8.89			0.350	
F	3.8		4.0	0.149		0.157
G	4.6		5.3	0.181		0.208
L	0.5		1.27	0.019		0.050
M			0.62			0.024
S	8° (max.)					



PO13H

TSSOP16 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			1.2			0.047
A1	0.05		0.15	0.002	0.004	0.006
A2	0.8	1	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.0089
D	4.9	5	5.1	0.193	0.197	0.201
E	6.2	6.4	6.6	0.244	0.252	0.260
E1	4.3	4.4	4.48	0.169	0.173	0.176
e		0.65 BSC			0.0256 BSC	
K	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030



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